



## TPUTTY 506



### GAP FILLER MATERIAL

#### Soft Silicone Putty

Tputty 506 is a soft single part silicone putty thermal gap filler in which no cure is required. This gap filler is ideal for applications where large gap tolerances are present and in which traditional gap filler pads may apply added pressure on components. This material can be dispensed to fill large and uneven gaps in assemblies.

Tputty 506 has a composition which yields superior thermal performance and super compliancy. This material transfers little to no pressure between interfaces. Tputty 506 is non-abrasive which leads to less wear on dispensing equipment and therefore reduced equipment maintenance/repair costs.



Prototyping  
Available



Custom Solutions



Standard Stock



Samples Available

## Features

- Soft and compliant transferring little to no pressure between interfaces
- Non-abrasive
- 3.5 W/mK thermal conductivity
- Available in 75 cc 180 cc 360 cc and 600 cc dispensing cartridges
- Available in 20 kg pails
- Easily dispensable from an EFD dispensing system

## Specifications

<p><b>Additional Product Description</b> Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.</p>	<p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Microprocessors</li> <li>• Graphic chips</li> <li>• Automotive</li> <li>• LED lighting</li> </ul>
<p><b>Color</b> Turquoise</p>	<p><b>Freq. Range 2.5 to 8 GHz</b> DEFAULT</p>
<p><b>Product Line</b> Tputty 506 Series</p>	<p><b>Temperature Range (Max Celsius)</b> 200.00</p>
<p><b>Temperature Range (Min Celsius)</b> -45.00</p>	<p><b>Thermal Conductivity</b> 3.50</p>
<p><b>UL Flammability</b> V0</p>	<p><b>Volume Resistivity</b> Volume Resistivity Del 1.8</p>
<p><b>_OTHER</b> Construction &amp; Composition - Fully Cured Ceramic-filled dispensable silicone putty</p> <p>Flow Rate (75 cc taper tip 0.125" orifice 90 psi) – 17.2 cc/min</p> <p>Abrasiveness of Predominant Filler - 2</p> <p>Minimum Bondline thickness mm (in) -0.1 (0.004)</p> <p>Outgassing TML weight percent -0.46%</p> <p>Outgassing TML volume percent -0.79%</p> <p>Coefficient of Volumetric Expansion (CVE) -680 ppm/K</p> <p>Coefficient of Thermal Expansion (CTE) -227 ppm/K</p> <p>Tg &lt; -90°C</p> <p>Specific Heat -0.85 J/gK</p>	